

HRC0203B

Silicon Schottky Barrier Diode for Rectifying

REJ03G0148-0100Z
(Previous: ADE-208-800)
Rev.1.00
Nov.26.2003

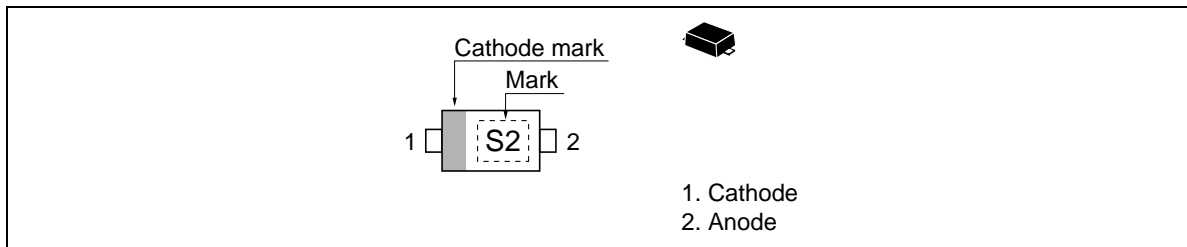
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HRC0203B	S2	UFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}^{*1}	30	V
Average rectified current	I_o^{*1}	200	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*2}	3	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

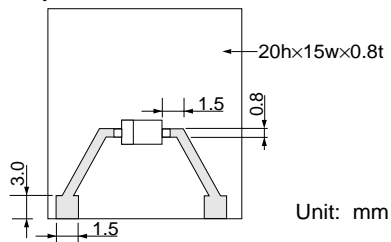
Notes: 1. See from Fig.3 to Fig.5.
 2. 10 ms sine wave 1 pulse.

Electrical Characteristics

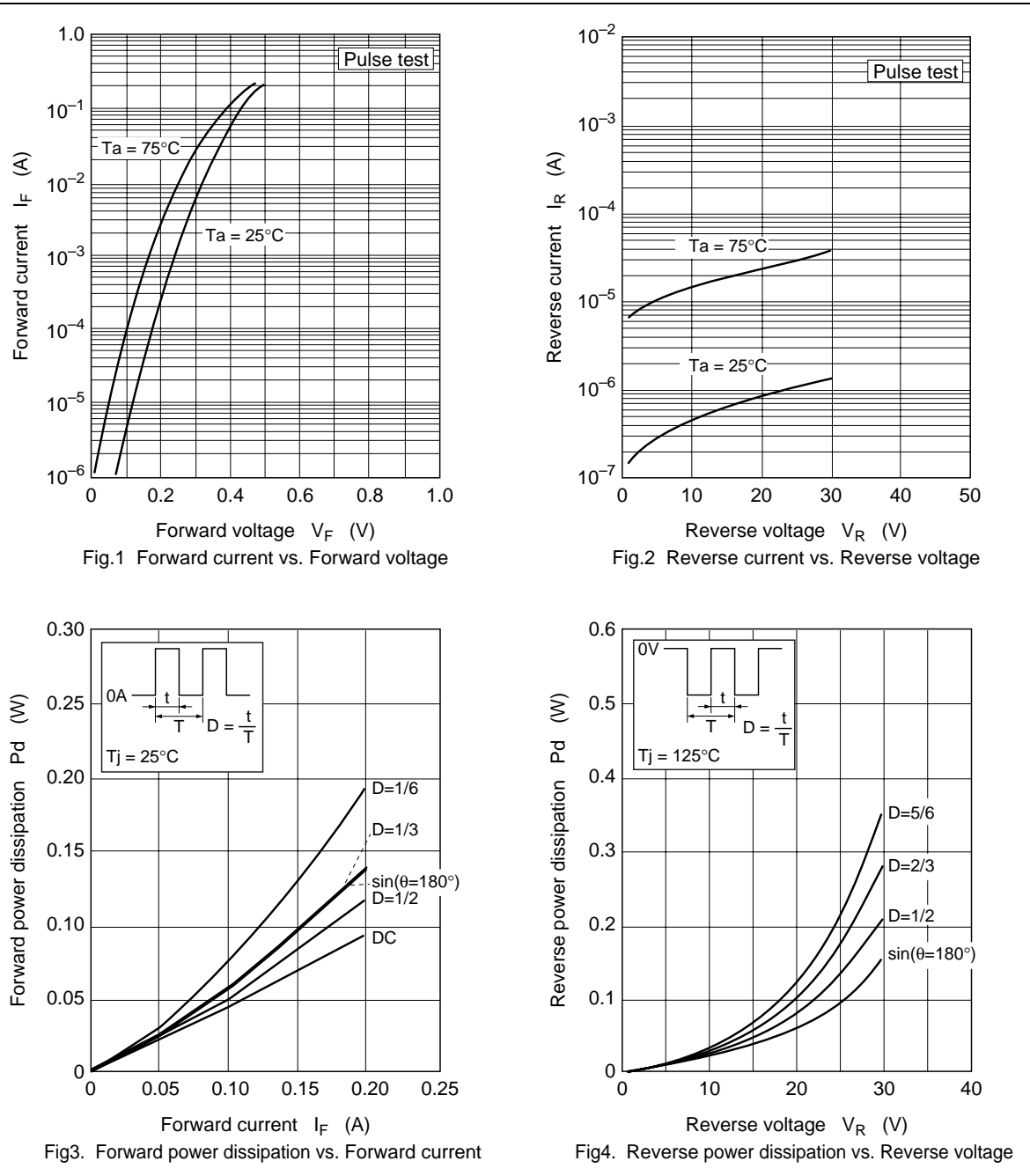
(Ta = 25°C)

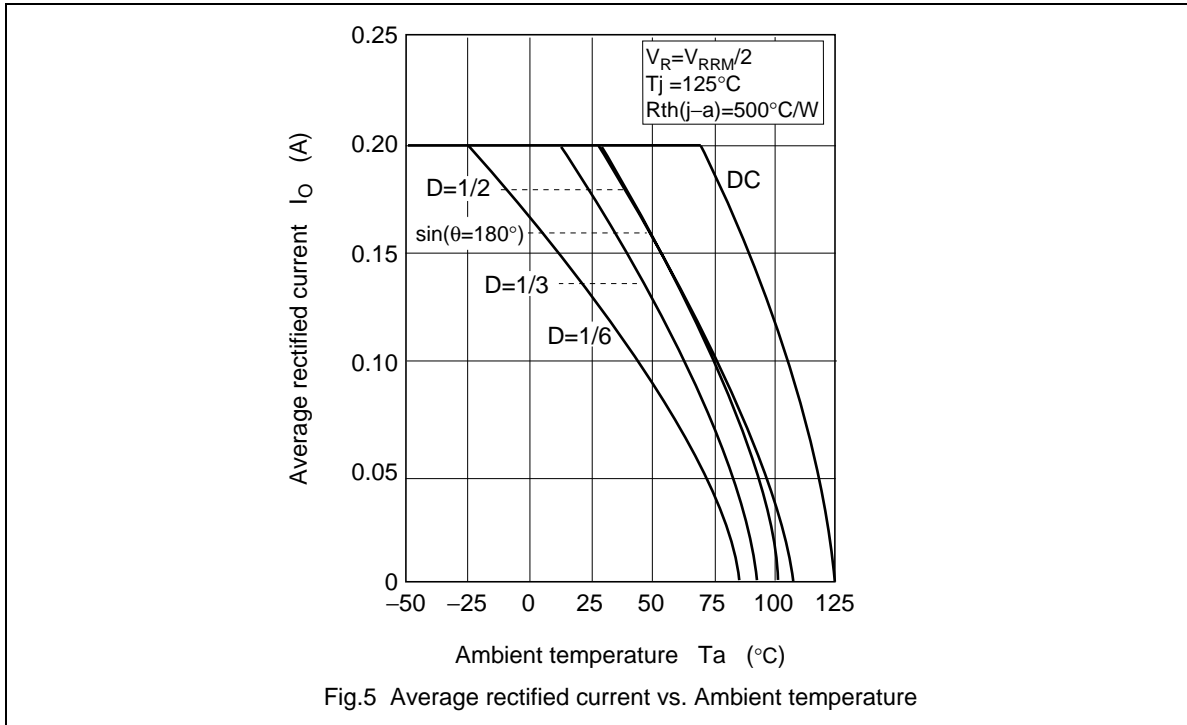
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.52	V	$I_F = 200 \text{ mA}$
Reverse current	I_R	—	—	10	μA	$V_R = 30 \text{ V}$
Thermal resistance	$R_{th(j-a)}$	—	500	—	°C/W	Polyimide board ^{*1}

Note: 1. Polyimide board



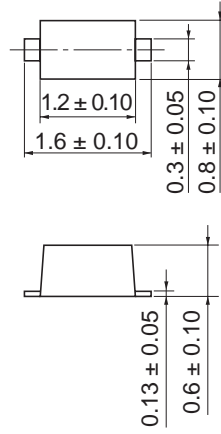
Main Characteristic





Package Dimensions

As of January, 2003
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001